



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_54731
Title of the Manuscript:	Wafer Thinning Process and its Critical Manufacturability Requirements
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments		
Minor REVISION comments	<ol style="list-style-type: none"> Sub-point numbering is not consistent - there is a point 1.1 and no 1.2, the numbers of sub-points 2.1 and 4.7 are duplicated. There are sub-points with very little content - 2.1. References are very small - only 5. 	
Optional/General comments	Maybe value and unit must be separate words - "200mm" -> 200 mm.	

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	<i>(If yes, Kindly please write down the ethical issues here in details)</i>	

Reviewer Details:

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